

POLISHING PAD

ABSTRACT

A polishing pad comprising at least a polishing layer and a cushion layer, wherein a groove is formed on a polishing surface of the polishing pad, at least one of angles formed by the polishing surface and a side surface of the groove which continues to the polishing surface is $105-150^{\circ}$ inclusive, and the cushion layer has a strain constant of 7.3×10^{-6} to 4.4×10^{-4} $\mu\text{m}/\text{Pa}$ inclusive. The use of the polishing pad can achieve a purpose of preventing the fluctuation in a polishing rate while keeping the polishing rate at a high level.

Figure 2